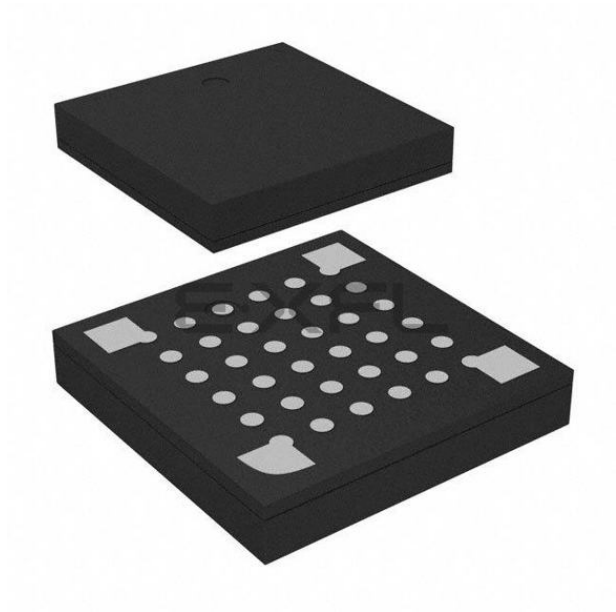
Renesas Electronics America Inc - R7FS124762A01CLM#AC1 Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	CANbus, I²C, SCI, SPI, UART/USART, USB
Peripherals	LVD, POR, PWM, WDT
Number of I/O	25
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 5.5V
Data Converters	A/D 11x14b; D/A 1x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	36-WFLGA
Supplier Device Package	36-WFLGA (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r7fs124762a01clm-ac1

1.7 Pin Lists

Pin number					Power, System, Clock, Debug, CAC	I/O ports	Timers				Communication Interfaces				Analogs		HMI	
LQFP64, QFN64	LQFP48	QFN48	QFN40	LGA36			AGT	GPT_OPS, POEG	GPT	RTC	USBFS,CAN	SCI	IIC	SPI	ADC14	DAC12, ACMPLP	CTSU	Interrupt
1	1	1	1	C2	CACREF_C	P400	AGTIO1_D		GTIOC6A_A			SCK0_B/SCK1_B	SCL0_A				TS20	IRQ0
2	2	2	-	-		P401		GTETRGA_B	GTIOC6B_A		CTX0_B	CTS0_RTS0_B/SS0_B/TXD1_B/MOSI1_B/SDA1_B	SDA0_A				TS19	IRQ5
3	-	-	-	-		P402					CRX0_B	RXD1_B/MISO1_B/SCL1_B					TS18	IRQ4
4	-	-	-	-		P403			GTIOC3A_B			CTS1_RTS1_B/SS1_B					TS17	
5	3	3	2	A1	VCL													
6	4	4	3	B1	XCIN	P215												
7	5	5	4	C1	XCOUT	P214												
8	6	6	5	D1	VSS													
9	7	7	6	D3	XTAL	P213		GTETRGA_D				TXD1_A/MOSI1_A/SDA1_A						IRQ2
10	8	8	7	D2	EXTAL	P212	AGTEE1	GTETRGB_D				RXD1_A/MISO1_A/SCL1_A						IRQ3
11	9	9	8	E1	VCC													
12	-	-	-	-		P411	AGTOA1	GTOVUP_B	GTIOC6A_B			TXD0_B/MOSI0_B/SDA0_B		MOSIA_B			TS07	IRQ4
13	-	-	-	-		P410	AGTOB1	GTOVLO_B	GTIOC6B_B			RXD0_B/MISO0_B/SCL0_B		MISOA_B			TS06	IRQ5
14	10	10	-	-		P409		GTOWUP_B	GTIOC5A_B			TXD9_A/MOSI9_A/SDA9_A					TS05	IRQ6
15	11	11	9	-		P408		GTOWLO_B	GTIOC5B_B			RXD9_A/MISO9_A/SCL9_A					TS04	IRQ7
16	12	12	10	E2		P407				RTCOUT	USB_VBUS	CTS0_RTS0_D/SS0_D	SDA0_B	SSLB3_A	ADTRG0_B		TS03	
17	13	13	11	F1	VSS_USB													
18	14	14	12	F2							USB_DM							
19	15	15	13	F3							USB_DP							
20	16	16	14	F4	VCC_USB													
21	17	17	15	F5	VCC_USB_LDO													
22	18	18	-	-		P206		GTIU_A				RXD0_D/MISO0_D/SCL0_D	SDA1_A	SSLB1_A			TS01	IRQ0
23	-	-	-	-	CLKOUT_A	P205	AGTO1	GTIV_A	GTIOC4A_B			TXD0_D/MOSI0_D/SDA0_D/CTS9_RTS9_A/SS9_A	SCL1_A	SSLB0_A			TSCAP_A	IRQ1
24	-	-	-	-	CACREF_A	P204	AGTIO1_A	GTIW_A	GTIOC4B_B			SCK0_D/SCK9_A	SCL0_B	RSPCKB_A			TS00	
25	19	19	16	E3	RES													
26	20	20	17	E4	MD	P201												
27	21	21	18	E5		P200												NMI
28	-	-	-	-		P304			GTIOC1A_B									
29	-	-	-	-		P303			GTIOC1B_B								TS02	
30	22	22	-	-		P302		GTOUUP_A	GTIOC4A_A					SSLB3_B			TS08	IRQ5
31	23	23	19	-		P301		GTOULO_A	GTIOC4B_A					SSLB2_B			TS09	IRQ6
32	24	24	20	F6	SWCLK	P300		GTOUUP_C	GTIOC0A_A					SSLB1_B				
33	25	25	21	E6	SWDIO	P108		GTOULO_C	GTIOC0B_A			CTS9_RTS9_B/SS9_B		SSLB0_B				
34	26	26	22	D4	CLKOUT_B	P109		GTOVUP_A	GTIOC1A_A		CTX0_A	TXD9_B/MOSI9_B/SDA9_B		MOSIB_B			TS10	

Pin number					Power, System, Clock, Debug, CAC	I/O ports	Timers				Communication Interfaces				Analogs		HMI	
LQFP64, QFN64	LQFP48	QFN48	QFN40	LGA36			AGT	GPT_OPS, POEG	GPT	RTC	USBFS,CAN	SCI	IIC	SPI	ADC14	DAC12, ACMPLP	CTSU	Interrupt
35	27	27	23	D5		P110		GTOVLO_A	GTIOC1B_A		CRX0_A	CTS0_RTS0_C/SS0_C/RXD9_B/MISO9_B/SCL9_B		MISOB_B		VCOUT	TS11	IRQ3
36	28	28	24	D6		P111			GTIOC3A_A			SCK0_C/SCK9_B		RSPCKB_B			TS12	IRQ4
37	29	29	25	C6		P112			GTIOC3B_A			TXD0_C/MOSI0_C/SDA0_C					TSCAP_C	
38	-	-	-	-		P113												
39	30	30	-	-	VCC													
40	31	31	-	-	VSS													
41	-	-	-	-		P107			GTIOC0A_B									KR07
42	-	-	-	-		P106			GTIOC0B_B					SSLA3_A				KR06
43	-	-	-	-		P105		GTETRGA_C						SSLA2_A				KR05/IRQ0
44	32	32	26	-		P104		GTETRGB_B				RXD0_C/MISO0_C/SCL0_C		SSLA1_A			TS13	KR04/IRQ1
45	33	33	27	C3		P103		GTOWUP_A	GTIOC2A_A		CTX0_C	CTS0_RTS0_A/SS0_A		SSLA0_A	AN019	CMPREF1	TS14	KR03
46	34	34	28	C4		P102	AGTO0	GTOWLO_A	GTIOC2B_A		CRX0_C	SCK0_A		RSPCKA_A	AN020/ADTRG0_A	CMPIN1	TS15	KR02
47	35	35	29	C5		P101	AGTEE0	GTETRGB_A	GTIOC5A_A			TXD0_A/MOSI0_A/SDA0_A/CTS1_RTS1_A/SS1_A	SDA1_B	MOSIA_A	AN021	CMPREF0	TS16	KR01/IRQ1
48	36	36	30	B6		P100	AGTIO0_A	GTETRGA_A	GTIOC5B_A			RXD0_A/MISO0_A/SCL0_A/SCK1_A	SCL1_B	MISOA_A	AN022	CMPIN0	TS26	KR00/IRQ2
49	37	37	-	-		P500	AGTOA0	GTIU_B	GTIOC2A_B						AN016		TS27	
50	-	-	-	-		P501	AGTOB0	GTIV_B	GTIOC2B_B						AN017			
51	-	-	-	-		P502		GTIW_B	GTIOC3B_B						AN018			
52	38	38	31	A6		P015									AN010		TS28	IRQ7
53	39	39	32	A5		P014									AN009	DA0		
54	40	40	33	B5		P013									AN008			
55	41	41	34	B4		P012									AN007			
56	42	42	35	A4	AVCC0													
57	43	43	36	A3	AVSS0													
58	44	44	37	B3	VREFL0	P011									AN006		TS31	
59	45	45	38	A2	VREFH0	P010									AN005		TS30	
60	-	-	-	-		P004									AN004		TS25	IRQ3
61	-	-	-	-		P003									AN003		TS24	
62	46	46	-	-		P002									AN002		TS23	IRQ2
63	47	47	39	-		P001									AN001		TS22	IRQ7
64	48	48	40	B2		P000									AN000		TS21	IRQ6

Note: Several pin names have the added suffix of _A, _B, _C, and _D. The suffix can be ignored when assigning functionality.

Table 2.2 Recommended operating conditions

Parameter	Symbol	Value	Min	Typ	Max	Unit
Power supply voltages	VCC*1, *2	When USBFS is not used	1.6	-	5.5	V
		When USBFS is used USB Regulator Disable	VCC_USB	-	3.6	V
		When USBFS is used USB Regulator Enable	VCC_USB_LDO	-	5.5	V
	VSS		-	0	-	V
USB power supply voltages	VCC_USB	When USBFS is not used	-	VCC	-	V
		When USBFS is used USB Regulator Disable (Input)	3.0	3.3	3.6	V
	VCC_USB_LDO	When USBFS is not used	-	VCC	-	V
		When USBFS is used USB Regulator Enable	3.8	-	5.5	V
		When USBFS is used USB Regulator Disable	-	VCC	-	V
	VSS_USB		-	0	-	V
Analog power supply voltages	AVCC0*1, *2		1.6	-	5.5	V
	AVSS0		-	0	-	V
	VREFH0	When used as ADC14 Reference	1.6	-	AVCC0	V
	VREFL0		-	0	-	V

Note 1. Use AVCC0 and VCC under the following conditions:
AVCC0 and VCC can be set individually within the operating range when VCC ≥ 2.2 V and AVCC0 ≥ 2.2 V
AVCC0 = VCC when VCC < 2.2 V or AVCC0 < 2.2 V.

Note 2. When powering on the VCC and AVCC0 pins, power them on at the same time or the VCC pin first and then the AVCC0 pin.

2.2.5 I/O Pin Output Characteristics of Low Drive Capacity

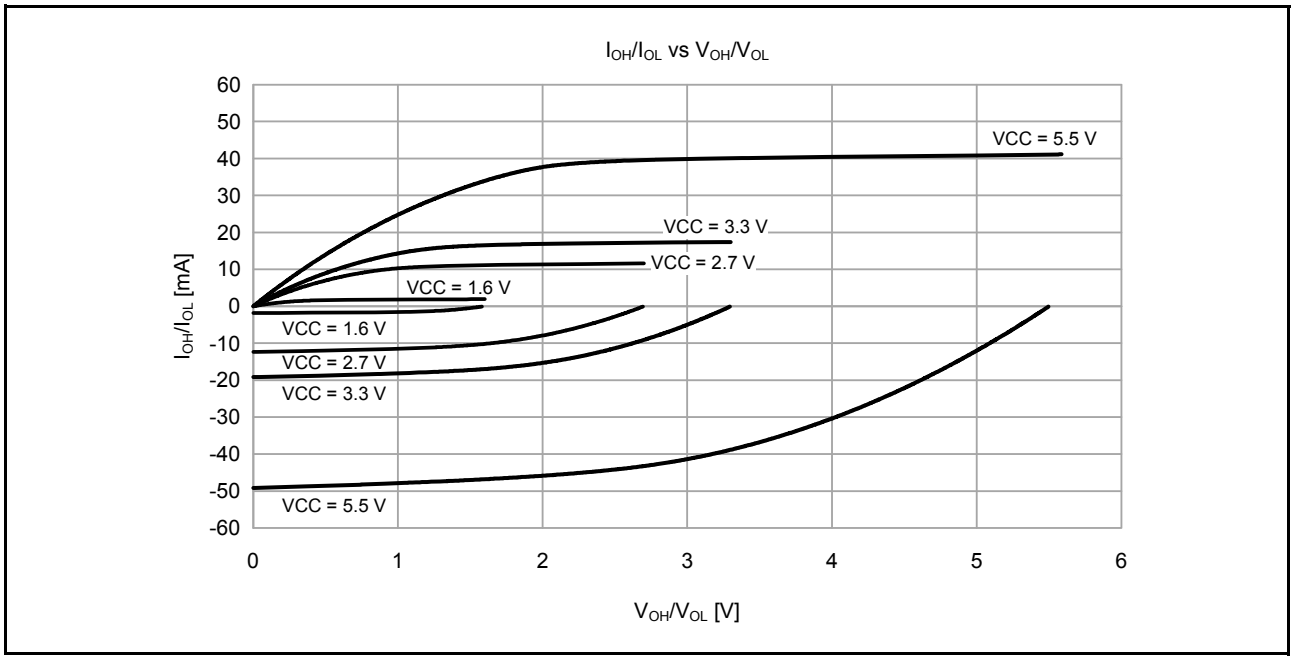


Figure 2.2 **V_{OH}/V_{OL} and I_{OH}/I_{OL} voltage characteristics at Ta = 25°C when low drive output is selected (reference data)**

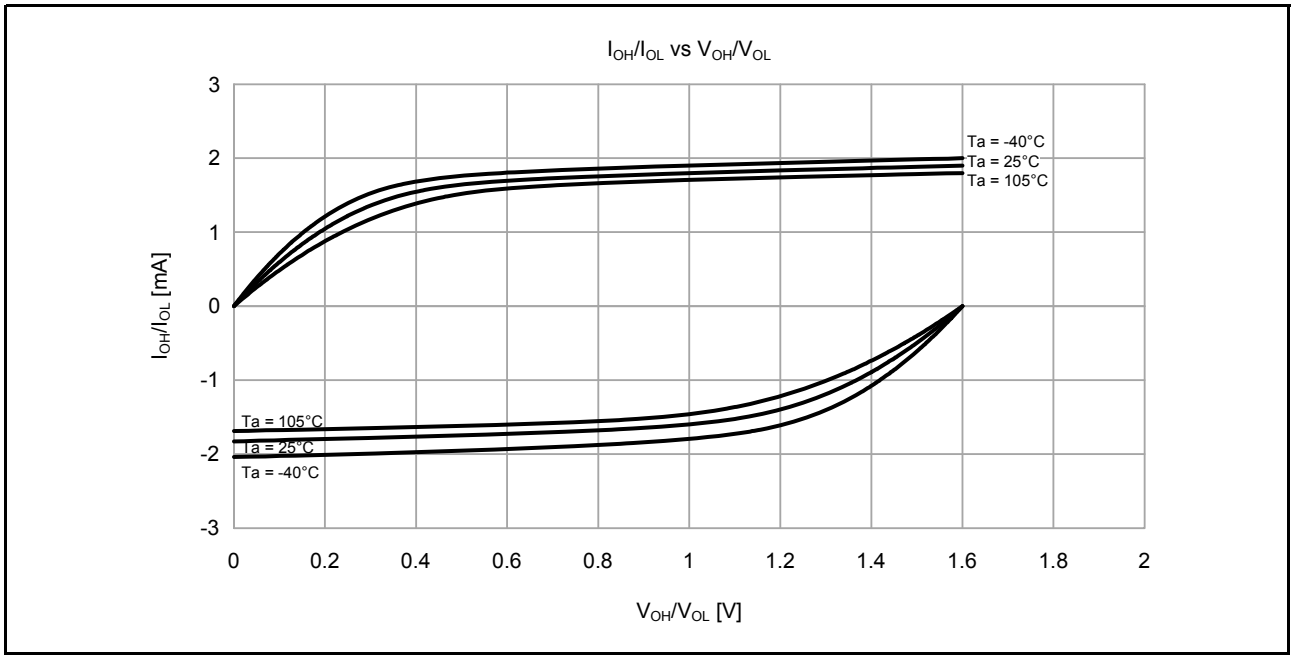


Figure 2.3 **V_{OH}/V_{OL} and I_{OH}/I_{OL} temperature characteristics at VCC = 1.6 V when low drive output is selected (reference data)**

2.2.9 Operating and Standby Current

Table 2.11 Operating and standby current (1) (1 of 2)
Conditions: VCC = AVCC0 = 1.6 to 5.5 V

Parameter					Symbol	Typ*9	Max	Unit	Test Conditions
Supply current*1	High-speed mode*2	Normal mode	All peripheral clock disabled, while (1) code executing from flash*5	ICLK = 32 MHz	I_{CC}	3.6	-	mA	*7
				ICLK = 16 MHz		2.4	-		
				ICLK = 8 MHz		1.7	-		
			All peripheral clock disabled, CoreMark code executing from flash*5	ICLK = 32 MHz		5.6	-		
				ICLK = 16 MHz		3.5	-		
				ICLK = 8 MHz		2.4	-		
			All peripheral clock enabled, while (1) code executing from flash*5	ICLK = 32 MHz		9.5	-		*8
				ICLK = 16 MHz		5.4	-		
				ICLK = 8 MHz		3.3	-		
			All peripheral clock enabled, code executing from flash*5	ICLK = 32 MHz		-	21.0		
		Sleep mode	All peripheral clock disabled*5	ICLK = 32 MHz		1.5	-		*7
				ICLK = 16 MHz		1.1	-		
				ICLK = 8 MHz		0.9	-		
			All peripheral clock enabled*5	ICLK = 32 MHz		7.2	-		*8
				ICLK = 16 MHz		4.0	-		
				ICLK = 8 MHz		2.4	-		
		Increase during BGO operation*6				2.5	-		-
	Middle-speed mode*2	Normal mode	All peripheral clock disabled, while (1) code executing from flash*5	ICLK = 12 MHz	I_{CC}	1.7	-	mA	*7
				ICLK = 8 MHz		1.5	-		
			All peripheral clock disabled, CoreMark code executing from flash*5	ICLK = 12 MHz		2.7	-		
				ICLK = 8 MHz		1.9	-		
			All peripheral clock enabled, while (1) code executing from flash*5	ICLK = 12 MHz		3.9	-		*8
				ICLK = 8 MHz		3.0	-		
			All peripheral clock enabled, code executing from flash*5	ICLK = 12 MHz		-	8.0		
		Sleep mode	All peripheral clock disabled*5	ICLK = 12 MHz		0.8	-		*7
				ICLK = 8 MHz		0.8	-		
			All peripheral clock enabled*5	ICLK = 12 MHz		2.9	-		*8
				ICLK = 8 MHz		2.2	-		
		Increase during BGO operation*6				2.5	-		-
	Low-speed mode*3	Normal mode	All peripheral clock disabled, while (1) code executing from flash*5	ICLK = 1 MHz	I_{CC}	0.2	-	mA	*7
			All peripheral clock disabled, CoreMark code executing from flash*5	ICLK = 1 MHz		0.3	-		
			All peripheral clock enabled, while (1) code executing from flash*5	ICLK = 1 MHz		0.4	-		*8
			All peripheral clock enabled, code executing from flash*5	ICLK = 1 MHz		-	2.0		
		Sleep mode	All peripheral clock disabled*5	ICLK = 1 MHz		0.2	-		*7
			All peripheral clock enabled*5	ICLK = 1 MHz		0.3	-		*8

2.2.10 VCC Rise and Fall Gradient and Ripple Frequency

Table 2.14 Rise and fall gradient characteristics
Conditions: VCC = AVCC0 = 0 to 5.5 V

Parameter		Symbol	Min	Typ	Max	Unit	Test conditions
Power-on VCC rising gradient	Voltage monitor 0 reset disabled at startup	SrVCC	0.02	-	2	ms/V	-
	Voltage monitor 0 reset enabled at startup*1, *2		0.02	-	-		
	SCI Boot mode*2		0.02	-	2		

Note 1. When OFS1.LVDAS = 0.
Note 2. At boot mode, the reset from voltage monitor 0 is disabled regardless of the value of OFS1.LVDAS bit.

Table 2.15 Rising and falling gradient and ripple frequency characteristics
Conditions: VCC = AVCC0 = 1.6 to 5.5 V
The ripple voltage must meet the allowable ripple frequency $f_{r(VCC)}$ within the range between the VCC upper limit (5.5 V) and lower limit (1.6 V).
When the VCC change exceeds VCC ±10%, the allowable voltage change rising and falling gradient dt/dVCC must be met.

Parameter	Symbol	Min	Typ	Max	Unit	Test conditions
Allowable ripple frequency	$f_{r\ (VCC)}$	-	-	10	kHz	Figure 2.24 $V_{r\ (VCC)} \leq VCC \times 0.2$
		-	-	1	MHz	Figure 2.24 $V_{r\ (VCC)} \leq VCC \times 0.08$
		-	-	10	MHz	Figure 2.24 $V_{r\ (VCC)} \leq VCC \times 0.06$
Allowable voltage change rising and falling gradient	dt/dVCC	1.0	-	-	ms/V	When VCC change exceeds VCC ±10%

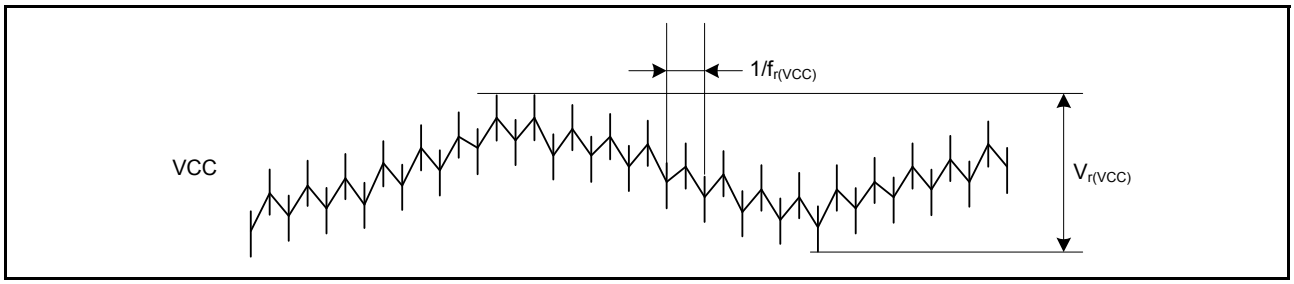


Figure 2.24 Ripple waveform

2.3 AC Characteristics

2.3.1 Frequency

Table 2.16 Operation frequency in high-speed operating mode
Conditions: VCC = AVCC0 = 2.4 to 5.5 V

Parameter			Symbol	Min	Typ	Max*5	Unit
Operation frequency	System clock (ICLK)*1, *2, *4	2.7 to 5.5 V	f	0.032768	-	32	MHz
		2.4 to 2.7 V		0.032768	-	16	
	Peripheral module clock (PCLKB)*4	2.7 to 5.5 V		-	-	32	
		2.4 to 2.7 V		-	-	16	
	Peripheral module clock (PCLKD)*3, *4	2.7 to 5.5 V		-	-	64	
		2.4 to 2.7 V		-	-	16	

Note 1. The lower-limit frequency of ICLK is 1 MHz while programming or erasing the flash memory. When using ICLK for programming or erasing the flash memory at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.
Note 2. The frequency accuracy of ICLK must be ±3.5% while programming or erasing the flash memory. Confirm the frequency accuracy of the clock source.
Note 3. The lower-limit frequency of PCLKD is 4 MHz at 2.4 V or above and 1 MHz at below 2.4 V when the 14-bit A/D converter is in use.
Note 4. See section 8, Clock Generation Circuit in User's Manual for the relationship of frequencies between ICLK, PCLKB, and PCLKD.
Note 5. The maximum value of operation frequency does not include internal oscillator errors. For details on the range of guaranteed operation, see Table 2.21, Clock timing.

Table 2.17 Operation frequency in middle-speed mode
Conditions: VCC = AVCC0 = 1.8 to 5.5 V

Parameter			Symbol	Min	Typ	Max*5	Unit
Operation frequency	System clock (ICLK)*1, *2, *4	2.7 to 5.5 V	f	0.032768	-	12	MHz
		2.4 to 2.7 V		0.032768	-	12	
		1.8 to 2.4 V		0.032768	-	8	
	Peripheral module clock (PCLKB)*4	2.7 to 5.5 V		-	-	12	
		2.4 to 2.7 V		-	-	12	
		1.8 to 2.4 V		-	-	8	
	Peripheral module clock (PCLKD)*3, *4	2.7 to 5.5 V		-	-	12	
		2.4 to 2.7 V		-	-	12	
		1.8 to 2.4 V		-	-	8	

Note 1. The lower-limit frequency of ICLK is 1 MHz while programming or erasing the flash memory. When using ICLK for programming or erasing the flash memory at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.
Note 2. The frequency accuracy of ICLK must be ±3.5% while programming or erasing the flash memory. Confirm the frequency accuracy of the clock source.
Note 3. The lower-limit frequency of PCLKD is 4 MHz at 2.4 V or above and 1 MHz at below 2.4 V when the 14-bit A/D converter is in use.
Note 4. See section 8, Clock Generation Circuit in User's Manual for the relationship of frequencies between ICLK, PCLKB, and PCLKD.
Note 5. The maximum value of operation frequency does not include internal oscillator errors. For details on the range of guaranteed operation, see Table 2.21, Clock timing.

Table 2.18 Operation frequency in low-speed mode

Conditions: VCC = AVCC0 = 1.8 to 5.5 V

Parameter			Symbol	Min	Typ	Max*5	Unit
Operation frequency	System clock (ICLK)*1, *2, *4	1.8 to 5.5 V	f	0.032768	-	1	MHz
	Peripheral module clock (PCLKB)*4	1.8 to 5.5 V		-	-	1	
	Peripheral module clock (PCLKD)*3, *4	1.8 to 5.5 V		-	-	1	

Note 1. The lower-limit frequency of ICLK is 1 MHz while programming or erasing the flash memory.
Note 2. The frequency accuracy of ICLK must be ±3.5% while programming or erasing the flash memory. Confirm the frequency accuracy of the clock source.
Note 3. The lower-limit frequency of PCLKD is 1 MHz when the A/D converter is in use.
Note 4. See section 8, Clock Generation Circuit in User's Manual for the relationship of frequencies between ICLK, PCLKB, and PCLKD.
Note 5. The maximum value of operation frequency does not include internal oscillator errors. For details on the range of guaranteed operation, see Table 2.21, Clock timing.

Table 2.19 Operation frequency in low-voltage mode

Conditions: VCC = AVCC0 = 1.6 to 5.5 V

Parameter			Symbol	Min	Typ	Max*5	Unit
Operation frequency	System clock (ICLK)*1, *2, *4	1.6 to 5.5 V	f	0.032768	-	4	MHz
	Peripheral module clock (PCLKB)*4	1.6 to 5.5 V		-	-	4	
	Peripheral module clock (PCLKD)*3, *4	1.6 to 5.5 V		-	-	4	

Note 1. The lower-limit frequency of ICLK is 1 MHz while programming or erasing the flash memory. When using ICLK for programming or erasing the flash memory at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.
Note 2. The frequency accuracy of ICLK must be ±3.5% while programming or erasing the flash memory. Confirm the frequency accuracy of the clock source.
Note 3. The lower-limit frequency of PCLKD is 4 MHz at 2.4 V or above and 1 MHz at below 2.4 V when the 14-bit A/D converter is in use.
Note 4. See section 8, Clock Generation Circuit in User's Manual for the relationship of frequencies between ICLK, PCLKB, and PCLKD.
Note 5. The maximum value of operation frequency does not include internal oscillator errors. For details on the range of guaranteed operation, see Table 2.21, Clock timing.

Table 2.20 Operation frequency in Subosc-speed mode

Conditions: VCC = AVCC0 = 1.8 to 5.5 V

Parameter			Symbol	Min	Typ	Max	Unit
Operation frequency	System clock (ICLK)*1, *3	1.8 to 5.5 V	f	27.8528	32.768	37.6832	kHz
	Peripheral module clock (PCLKB)*3	1.8 to 5.5 V		-	-	37.6832	
	Peripheral module clock (PCLKD)*2, *3	1.8 to 5.5 V		-	-	37.6832	

Note 1. Programming and erasing the flash memory is not possible.
Note 2. The 14-bit A/D converter cannot be used.
Note 3. See section 8, Clock Generation Circuit in User's Manual for the relationship between ICLK, PCLKB, and PCLKD frequencies.

2.3.6 I/O Ports, POEG, GPT, AGT, KINT, and ADC14 Trigger Timing

Table 2.30 I/O Ports, POEG, GPT, AGT, KINT, and ADC14 trigger timing

Parameter			Symbol	Min	Max	Unit	Test conditions
I/O Ports	Input data pulse width		t_{PRW}	1.5	-	t_{Pcyc}	Figure 2.35
POEG	POEG input trigger pulse width		t_{POEW}	3	-	t_{Pcyc}	Figure 2.36
GPT	Input capture pulse width	Single edge	t_{GTICW}	1.5	-	t_{PDcyc}	Figure 2.37
		Dual edge		2.5	-		
AGT	AGTIO, AGTEE input cycle	2.7 V ≤ VCC ≤ 5.5 V	t_{ACYC}*1	250	-	ns	Figure 2.38
		2.4 V ≤ VCC < 2.7 V		500	-	ns	
		1.8 V ≤ VCC < 2.4 V		1000	-	ns	
		1.6 V ≤ VCC < 1.8 V		2000	-	ns	
	AGTIO, AGTEE input high level width, low-level width	2.7 V ≤ VCC ≤ 5.5 V	t_{ACKWH}, t_{ACKWL}	100	-	ns	
		2.4 V ≤ VCC < 2.7 V		200	-	ns	
		1.8 V ≤ VCC < 2.4 V		400	-	ns	
		1.6 V ≤ VCC < 1.8 V		800	-	ns	
	AGTIO, AGTO, AGTOA, AGTOB output cycle	2.7 V ≤ VCC ≤ 5.5 V	t_{ACYC2}	62.5	-	ns	Figure 2.38
		2.4 V ≤ VCC < 2.7 V		125	-	ns	
		1.8 V ≤ VCC < 2.4 V		250	-	ns	
		1.6 V ≤ VCC < 1.8 V		500	-	ns	
ADC14	14-bit A/D converter trigger input pulse width		t_{TRGW}	1.5	-	t_{Pcyc}	Figure 2.39
KINT	KRn (n = 00 to 07) pulse width		t_{KR}	250	-	ns	Figure 2.40

Note: tPcyc: PCLKB cycle, tPDcyc: PCLKD cycle.
Note 1. Constraints on AGTIO input: t_{Pcyc} × 2 (t_{Pcyc}: PCLKB cycle) < t_{ACYC}.

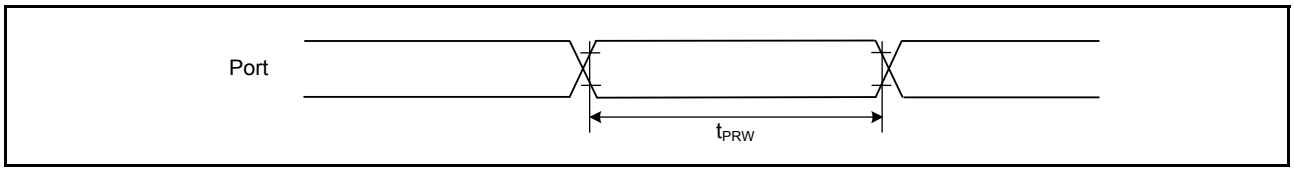


Figure 2.35 I/O ports input timing

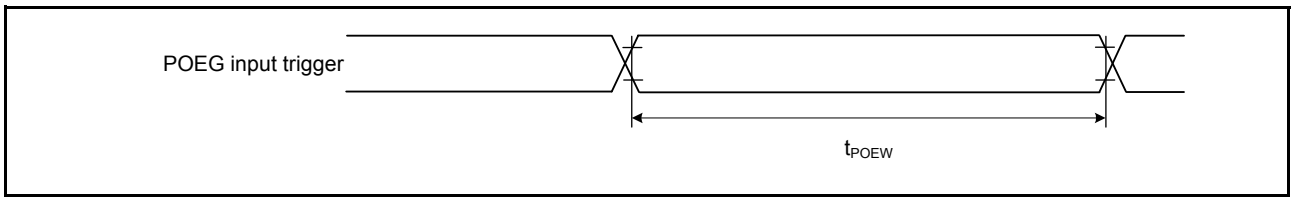


Figure 2.36 POEG input trigger timing

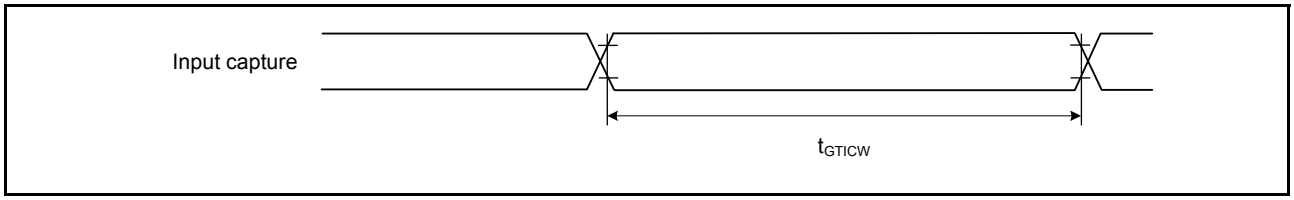


Figure 2.37 GPT input capture timing

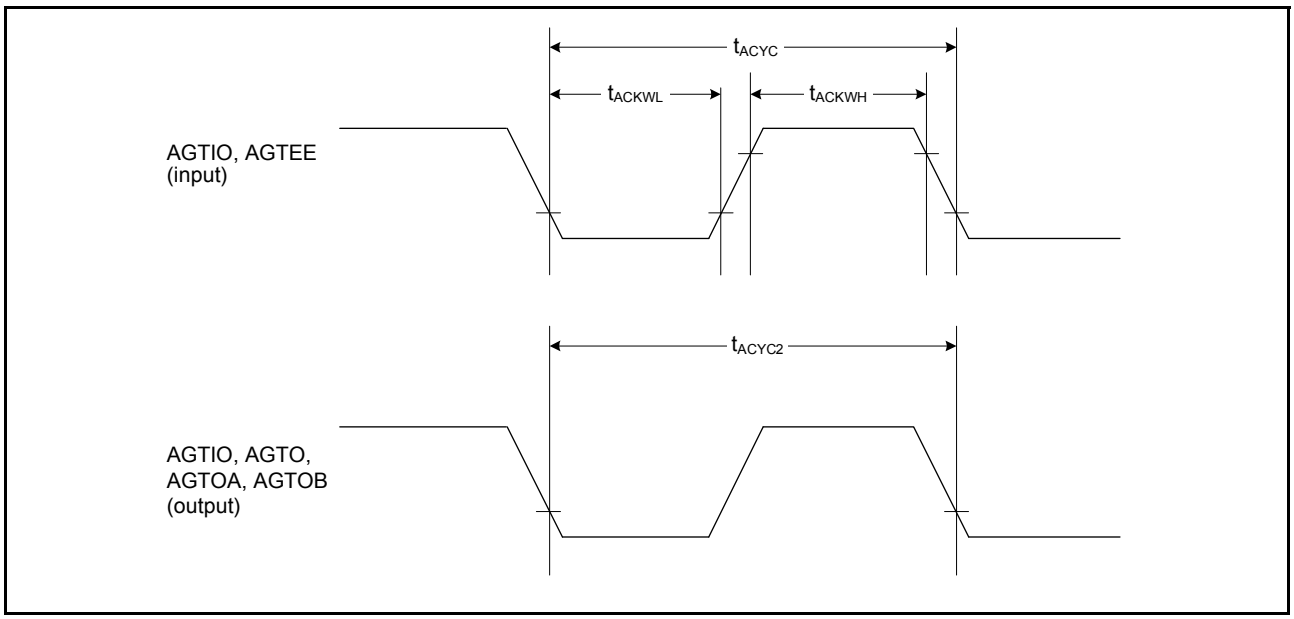


Figure 2.38 AGT I/O timing

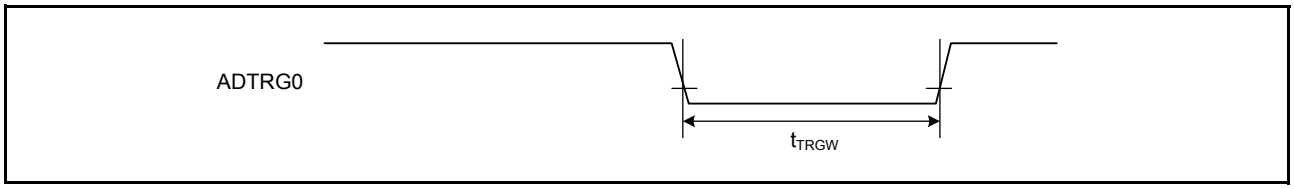


Figure 2.39 ADC14 trigger input timing

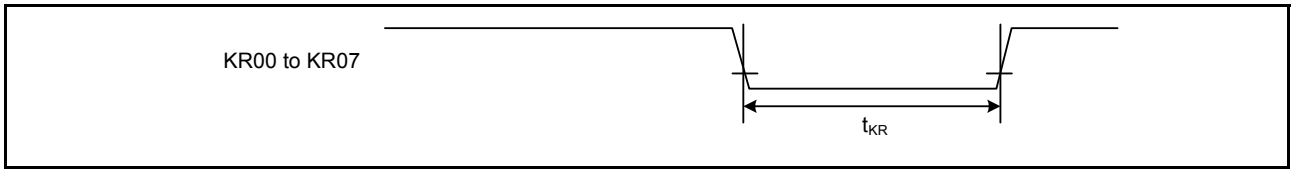


Figure 2.40 Key interrupt input timing

2.3.7 CAC Timing

Table 2.31 CAC timing

Parameter			Symbol	Min	Typ	Max	Unit	Test conditions
CAC	CACREF input pulse width	$t_{PBcyc} \leq tcac$*2	t_{CACREF}	$4.5 \times t_{cac} + 3 \times t_{PBcyc}$	-	-	ns	-
		$t_{PBcyc} > tcac$*2		$5 \times t_{cac} + 6.5 \times t_{PBcyc}$	-	-	ns	

Note 1. t_{PBcyc}: PCLKB cycle.

Table 2.33 SCI timing (2)
Conditions: VCC = AVCC0 = 1.6 to 5.5 V

Parameter				Symbol	Min	Max	Unit*1	Test conditions
Simple SPI	SCK clock cycle output (master)			t_{SPcyc}	4	65536	t_{Pcyc}	Figure 2.43
	SCK clock cycle input (slave)				6	65536		
	SCK clock high pulse width			t_{SPCKWH}	0.4	0.6	t_{SPcyc}	
	SCK clock low pulse width			t_{SPCKWL}	0.4	0.6	t_{SPcyc}	
	SCK clock rise and fall time		1.8V or above	t_{SPCKr}, t_{SPCKf}	-	20	ns	
			1.6V or above		-	30		
	Data input setup time	Master	2.7V or above	t_{SU}	45	-	ns	Figure 2.44 to Figure 2.47
			2.4V or above		55	-		
			1.8V or above		80	-		
			1.6V or above		110	-		
		Slave	2.7V or above		40	-		
			1.6V or above		45	-		
	Data input hold time	Master		t_H	33.3	-	ns	
		Slave			40	-		
	SS input setup time			t_{LEAD}	1	-	t_{SPcyc}	
	SS input hold time			t_{LAG}	1	-	t_{SPcyc}	
	Data output delay	Master	1.8V or above	t_{OD}	-	40	ns	
			1.6V or above		-	50		
		Slave	2.4V or above		-	65		
			1.8V or above		-	100		
			1.6V or above		-	125		
	Data output hold time	Master	2.7V or above	t_{OH}	–10	-	ns	
			2.4V or above		–20	-		
			1.8V or above		–30	-		
			1.6V or above		–40	-		
		Slave			–10	-		
	Data rise and fall time	Master	1.8V or above	t_{Dr}, t_{Df}	-	20	ns	
			1.6V or above		-	30		
		Slave	1.8V or above		-	20		
			1.6V or above		-	30		
Simple SPI	Slave access time			t_{SA}	-	6	t_{Pcyc}	Figure 2.47
	Slave output release time			t_{REL}	-	6	t_{Pcyc}	

Note 1. t_{Pcyc}: PCLKB cycle

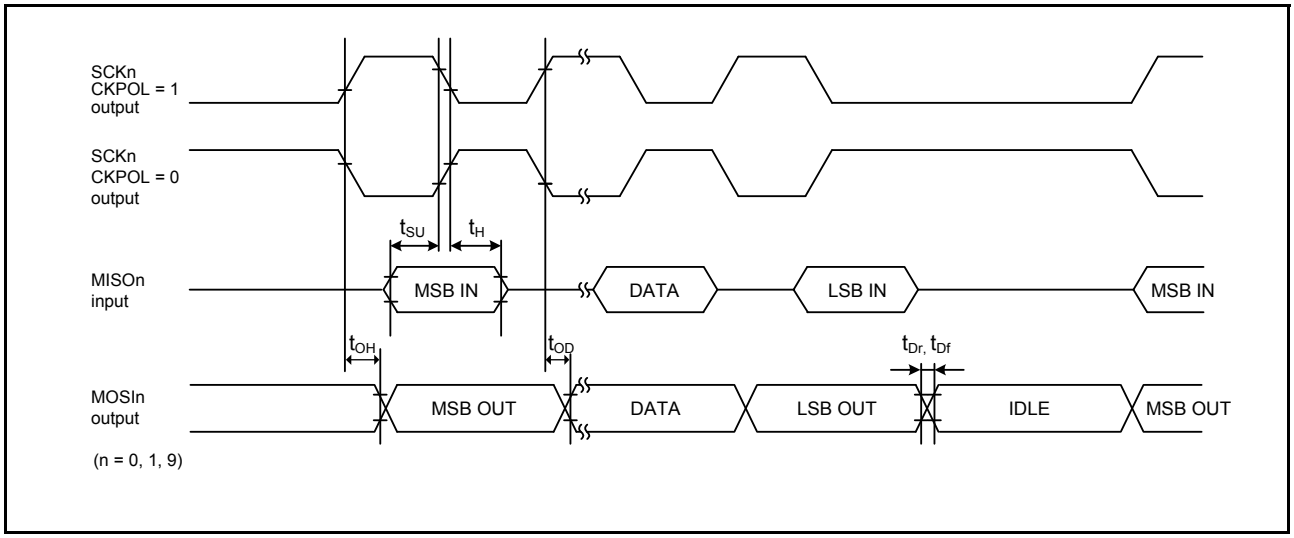


Figure 2.45 SCI simple SPI mode timing (master, CKPH = 0)

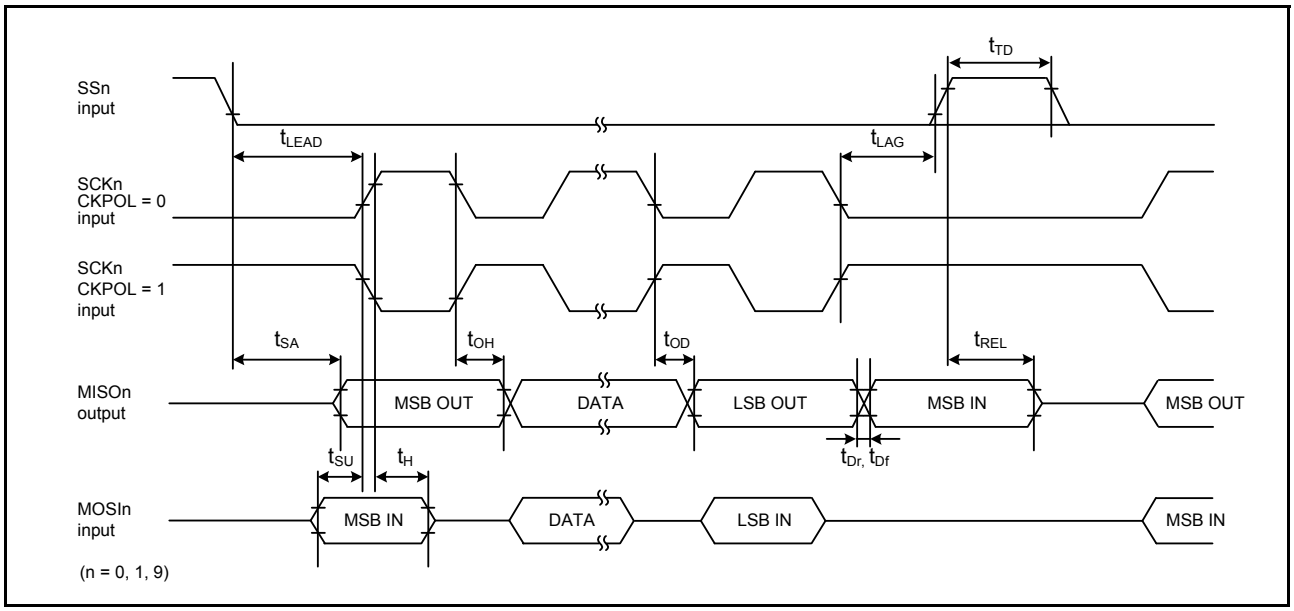


Figure 2.46 SCI simple SPI mode timing (slave, CKPH = 1)

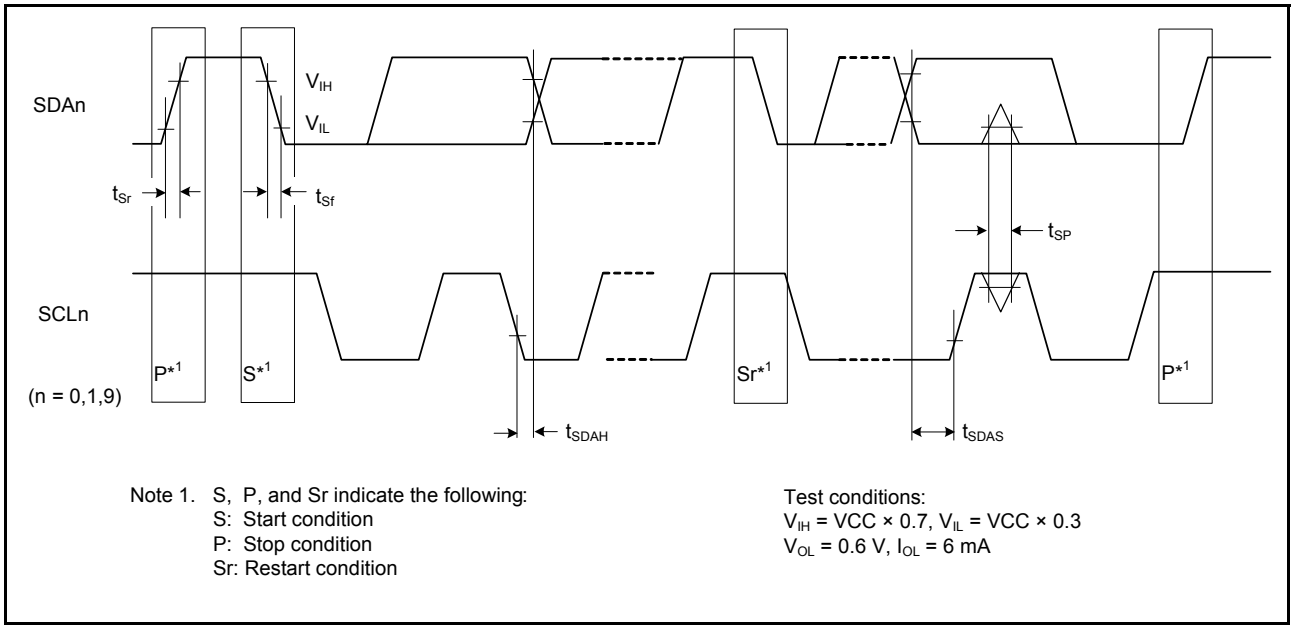


Figure 2.48 SCI simple IIC mode timing

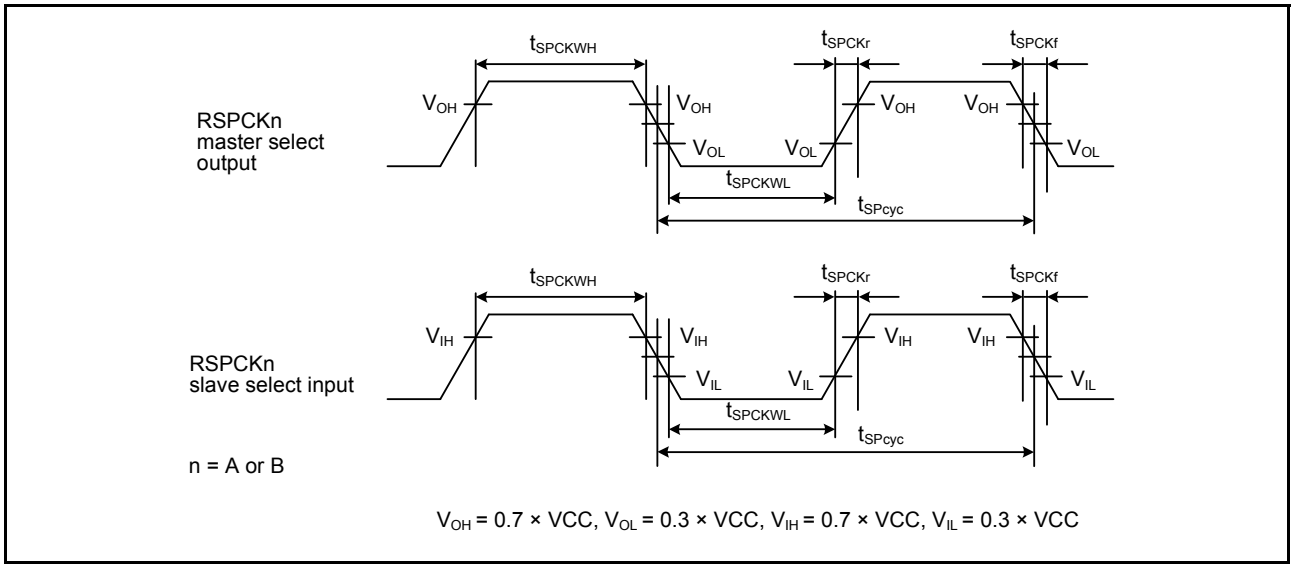


Figure 2.49 SPI clock timing

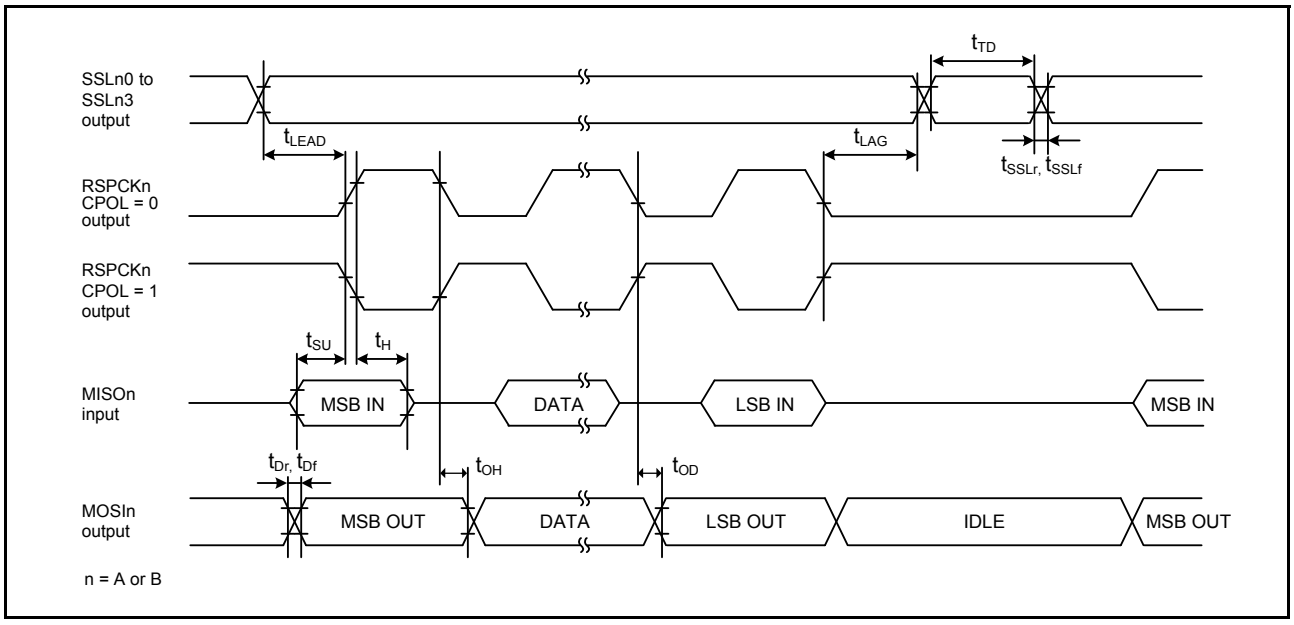
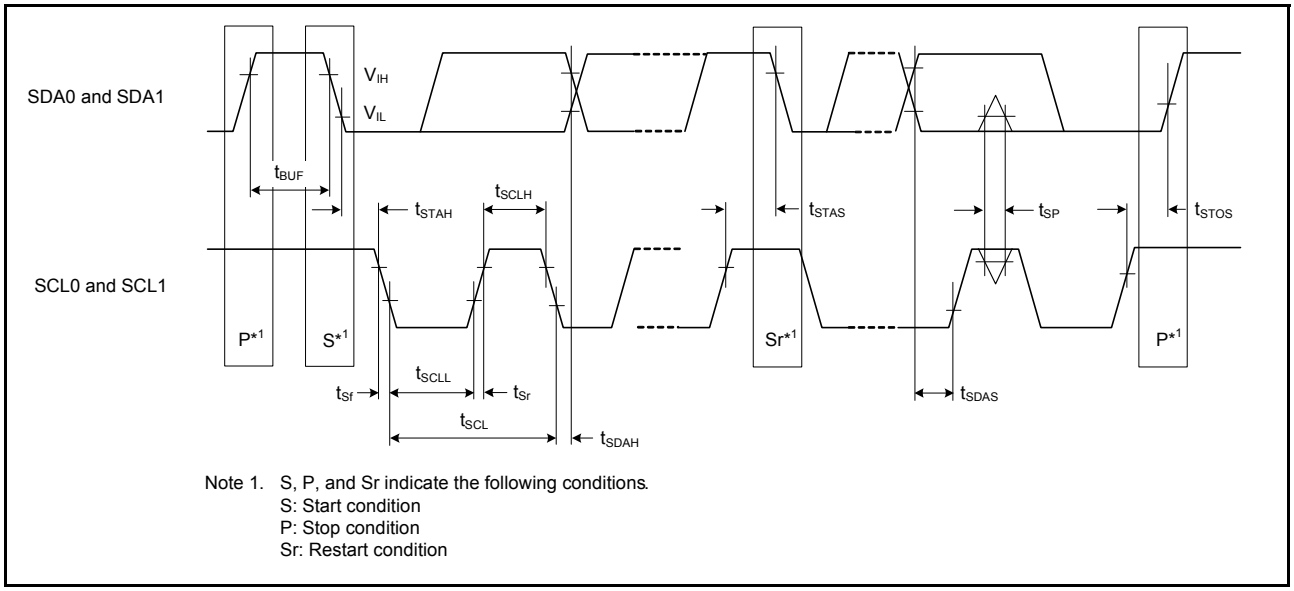


Figure 2.50 SPI timing (master, CPHA = 0) (bit rate: PCLKB division ratio is set to any value other than 1/2)



Note 1. S, P, and Sr indicate the following conditions.
S: Start condition
P: Stop condition
Sr: Restart condition

Figure 2.56 I²C bus interface input/output timing

2.12 Flash Memory Characteristics

2.12.1 Code Flash Memory Characteristics

Table 2.56 Code flash characteristics (1)

Parameter		Symbol	Min	Typ	Max	Unit	Conditions
Reprogramming/erasure cycle*1		N_{PEC}	1000	-	-	Times	-
Data hold time	After 1000 times N_{PEC}	t_{DRP}	20*2, *3	-	-	Year	T_a = +85°C

Note 1. The reprogram/erase cycle is the number of erasures for each block. When the reprogram/erase cycle is n times (n = 1,000), erasing can be performed n times for each block. For instance, when 4-byte programming is performed 256 times for different addresses in 1-KB blocks, and then the entire block is erased, the reprogram/erase cycle is counted as 1. However, programming the same address for several times as one erasure is not enabled. (overwriting is prohibited.)

Note 2. Characteristic when using the flash memory programmer and the self-programming library provided by Renesas Electronics.

Note 3. This result is obtained from reliability testing.

Table 2.57 Code flash characteristics (2)

High-speed operating mode

Conditions: VCC = AVCC0 = 2.7 to 5.5 V

Parameter		Symbol	ICLK = 1 MHz			ICLK = 32 MHz			Unit
			Min	Typ	Max	Min	Typ	Max	
Programming time	4-byte	t_{P4}	-	116	998	-	54	506	µs
Erasure time	1-KB	t_{E1K}	-	9.03	287	-	5.67	222	ms
Blank check time	4-byte	t_{BC4}	-	-	56.8	-	-	16.6	µs
	1-KB	t_{BC1K}	-	-	1899	-	-	140	µs
Erase suspended time		t_{SED}	-	-	22.5	-	-	10.7	µs
Startup area switching setting time		t_{SAS}	-	21.9	585	-	12.1	447	ms
Access window time		t_{AWS}	-	21.9	585	-	12.1	447	ms
OCD/serial programmer ID setting time		t_{OSIS}	-	21.9	585	-	12.1	447	ms
Flash memory mode transition wait time 1		t_{DIS}	2	-	-	2	-	-	µs
Flash memory mode transition wait time 2		t_{MS}	5	-	-	5	-	-	µs

Note 1. Does not include the time until each operation of the flash memory is started after instructions are executed by the software.

Note 2. The lower-limit frequency of ICLK is 1 MHz during programming or erasing the flash memory. When using ICLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.

Note 3. The frequency accuracy of ICLK must be ±3.5% while programming or erasing the flash memory. Confirm the frequency accuracy of the clock source.

Table 2.58 Code flash characteristics (3)

Middle-speed operating mode

Conditions: VCC = AVCC0 = 1.8 to 5.5 V, Ta = -40 to +85°C

Parameter		Symbol	ICLK = 1 MHz			ICLK = 8 MHz			Unit
			Min	Typ	Max	Min	Typ	Max	
Programming time	4-byte	t_{P4}	-	157	1411	-	101	966	µs
Erasure time	1-KB	t_{E1K}	-	9.10	289	-	6.10	228	ms
Blank check time	2-byte	t_{BC4}	-	-	87.7	-	-	52.5	µs
	1-KB	t_{BC1K}	-	-	1930	-	-	414	µs
Erase suspended time		t_{SED}	-	-	32.7	-	-	21.6	µs
Startup area switching setting time		t_{SAS}	-	22.8	592	-	14.2	465	ms
Access window time		t_{AWS}	-	22.8	592	-	14.2	465	ms
OCD/serial programmer ID setting time		t_{OSIS}	-	22.8	592	-	14.2	465	ms
Flash memory mode transition wait time 1		t_{DIS}	2	-	-	2	-	-	µs
Flash memory mode transition wait time 2		t_{MS}	720	-	-	720	-	-	ns

Note 1. Does not include the time until each operation of the flash memory is started after instructions are executed by the software.

Note 2. The lower-limit frequency of ICLK is 1 MHz during programming or erasing the flash memory. When using ICLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.

Note 3. The frequency accuracy of ICLK must be ±3.5% while programming or erasing the flash memory. Confirm the frequency accuracy of the clock source.

2.12.2 Data Flash Memory Characteristics

Table 2.59 Data flash characteristics (1)

Parameter		Symbol	Min	Typ	Max	Unit	Conditions
Reprogramming/erasure cycle*1		N_{DPEC}	100000	1000000	-	Times	-
Data hold time	After 10000 times of N_{DPEC}	t_{DDRP}	20*2, *3	-	-	Year	Ta = +85°C
	After 100000 times of N_{DPEC}		5*2, *3	-	-	Year	
	After 1000000 times of N_{DPEC}		-	1*2, *3	-	Year	Ta = +25°C

Note 1. The reprogram/erase cycle is the number of erasure for each block. When the reprogram/erase cycle is n times (n = 100,000), erasing can be performed n times for each block. For instance, when 1-byte programming is performed 1,000 times for different addresses in 1-byte blocks, and then the entire block is erased, the reprogram/erase cycle is counted as 1. However, programming the same address for several times as one erasure is not enabled. (overwriting is prohibited.)

Note 2. Characteristics when using the flash memory programmer and the self-programming library provided by Renesas Electronics.

Note 3. These results are obtained from reliability testing.

Table 2.60 Data flash characteristics (2)
High-speed operating mode
Conditions: VCC = AVCC0 = 2.7 to 5.5 V

Parameter		Symbol	ICLK = 4 MHz			ICLK = 32 MHz			Unit
			Min	Typ	Max	Min	Typ	Max	
Programming time	1-byte	t_{DP1}	-	52.4	463	-	42.1	387	µs
Erasure time	1-KB	t_{DE1K}	-	8.98	286	-	6.42	237	ms
Blank check time	1-byte	t_{DBC1}	-	-	24.3	-	-	16.6	µs
	1-KB	t_{DBC1K}	-	-	1872	-	-	512	µs
Suspended time during erasing		t_{DSED}	-	-	13.0	-	-	10.7	µs
Data flash STOP recovery time		t_{DSTOP}	5	-	-	5	-	-	µs

Note 1. Does not include the time until each operation of the flash memory is started after instructions are executed by the software.
Note 2. The lower-limit frequency of ICLK is 1 MHz during programming or erasing the flash memory. When using ICLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.
Note 3. The frequency accuracy of ICLK must be ±3.5% while programming or erasing the flash memory. Confirm the frequency accuracy of the clock source.

Table 2.61 Data flash characteristics (3)
Middle-speed operating mode
Conditions: VCC = AVCC0 = 1.8 to 5.5 V, Ta = -40 to +85°C

Parameter		Symbol	ICLK = 4 MHz			ICLK = 8 MHz			Unit
			Min	Typ	Max	Min	Typ	Max	
Programming time	1-byte	t_{DP1}	-	94.7	886	-	89.3	849	µs
Erasure time	1-KB	t_{DE1K}	-	9.59	299	-	8.29	273	ms
Blank check time	1-byte	t_{DBC1}	-	-	56.2	-	-	52.5	µs
	1-KB	t_{DBC1K}	-	-	2.17	-	-	1.51	ms
Suspended time during erasing		t_{DSED}	-	-	23.0	-	-	21.7	µs
Data flash STOP recovery time		t_{DSTOP}	720	-	-	720	-	-	ns

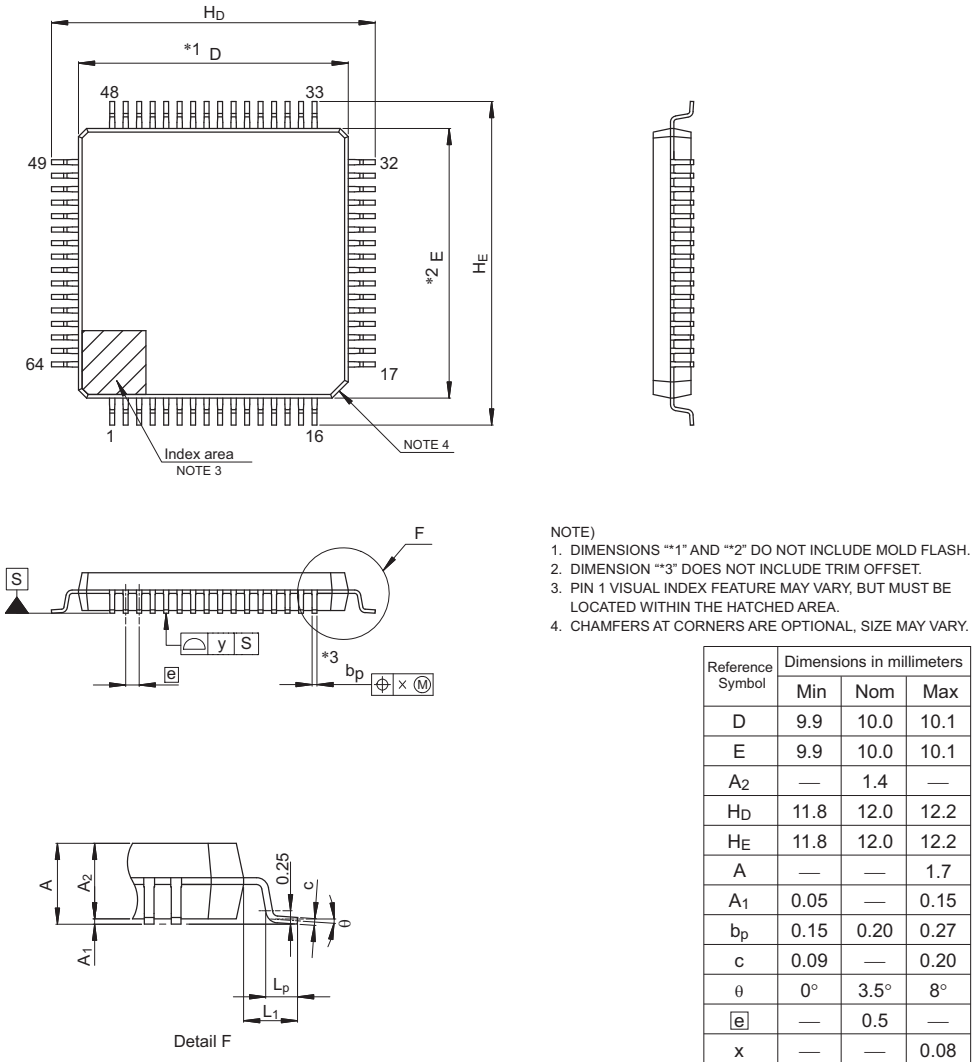
Note 1. Does not include the time until each operation of the flash memory is started after instructions are executed by the software.
Note 2. The lower-limit frequency of ICLK is 1 MHz during programming or erasing the flash memory. When using ICLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.
Note 3. The frequency accuracy of ICLK must be ±3.5% while programming or erasing the flash memory. Confirm the frequency accuracy of the clock source.

Appendix 1. Package Dimensions

Information on the latest version of the package dimensions or mountings is displayed in “Packages” on the Renesas Electronics Corporation website.

JEITA Package Code	RENESAS Code	Previous Code	MASS (Typ) [g]
P-LFQFP64-10x10-0.50	PLQP0064KB-C	—	0.3

Unit: mm



NOTE)
1. DIMENSIONS “*1” AND “*2” DO NOT INCLUDE MOLD FLASH.
2. DIMENSION “*3” DOES NOT INCLUDE TRIM OFFSET.
3. PIN 1 VISUAL INDEX FEATURE MAY VARY, BUT MUST BE LOCATED WITHIN THE HATCHED AREA.
4. CHAMFERS AT CORNERS ARE OPTIONAL, SIZE MAY VARY.

Reference Symbol	Dimensions in millimeters		
	Min	Nom	Max
D	9.9	10.0	10.1
E	9.9	10.0	10.1
A_2	—	1.4	—
H_D	11.8	12.0	12.2
H_E	11.8	12.0	12.2
A	—	—	1.7
A_1	0.05	—	0.15
b_p	0.15	0.20	0.27
c	0.09	—	0.20
θ	0°	3.5°	8°
e	—	0.5	—
x	—	—	0.08
y	—	—	0.08
L_p	0.45	0.6	0.75
L_1	—	1.0	—

Figure 1.1 LQFP 64-pin

General Precautions

1. Precaution against Electrostatic Discharge (ESD)

   A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

   The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

   Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

   Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

   After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

   Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

   Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

   Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.